

**Soldered SAM on water cooled copper heat sink with 25.0 mm diameter**  
**SAM- $\lambda$ -A- $\tau$ -4.0-25.0w-c or SAM- $\lambda$ -A- $\tau$ -4.0-25.0w-e**

SAM chip area            standard:        4.0 mm x 4.0 mm  
 Chip thickness           standard:        450  $\mu$ m  
 Front side protection   the SAM is protected with a dielectric front layer.

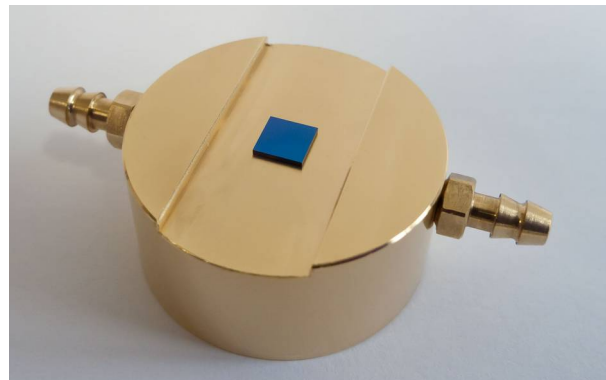
The SAM chip is soldered on a gold plated, water cooled copper mount with 25.0 mm diameter using a Sn/Bi solder. The solder provides a low thermal resistance between the SAM chip and the mount.

- The **standard** mounting position of the SAM is at the center of the heat sink  $\rightarrow x = 4.0-25.4w-c$ .
- **Optional** the SAM can be soldered on the edge of the heat sink without extra charges  
 $\rightarrow x = 4.0-25.4w-e$ .

Edge mounted: SAM- $\lambda$ -A-4.0-25.0w-e



Centre mounted: SAM- $\lambda$ -A-4.0-25.0w-c



Back side



This water cooled heat sink comes with a 2 m long water tube with an inner diameter of 3 mm.

**Recommended values for cooling water**

flow rate:                    1000 cm<sup>3</sup>/h = 17 cm<sup>3</sup>/min  
 pressure difference        0.03 bar  
 maximum pressure        1 bar

